

## SILICON GATE BICMOS

# **131,072 WORD x 8 BIT BiCMOS STATIC RAM**

## Description

The TC55B8128P/J is a 1,048,576 bit high speed BiCMOS static random access memory organized as 131,072 words by 8 bits and operated from a single 5V supply. Toshiba's BiCMOS technology and advanced circuit design enable high speed operation.

The TC55B8128P/J features low power dissipation when the device is deselected using chip enable (CE), and has an output enable input ( $\overline{OE}$ ) for fast memory access.

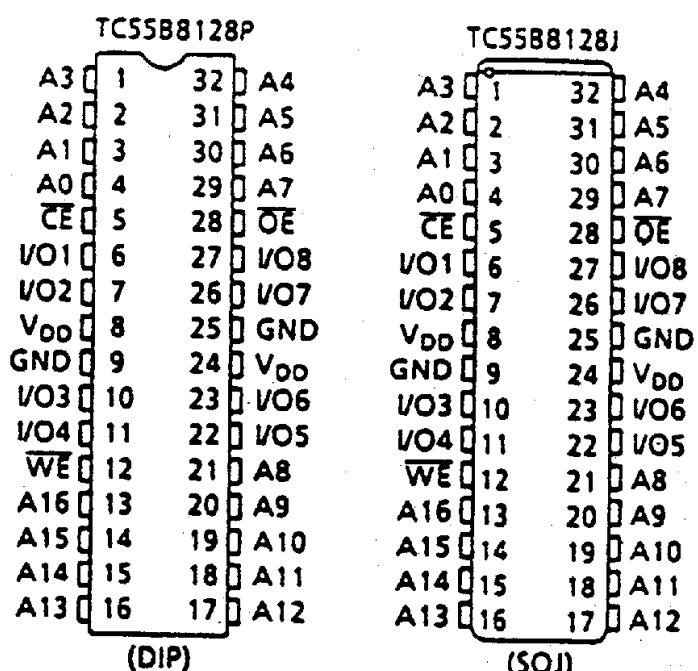
The TC55B8128P/J is suitable for use in high speed applications such as cache memory and high speed storage. All inputs and outputs are TTL compatible.

The TC55B8128P/J is available in a 400mil width, 32-pin DIP and SOJ suitable for high density surface assembly.

### **Features**

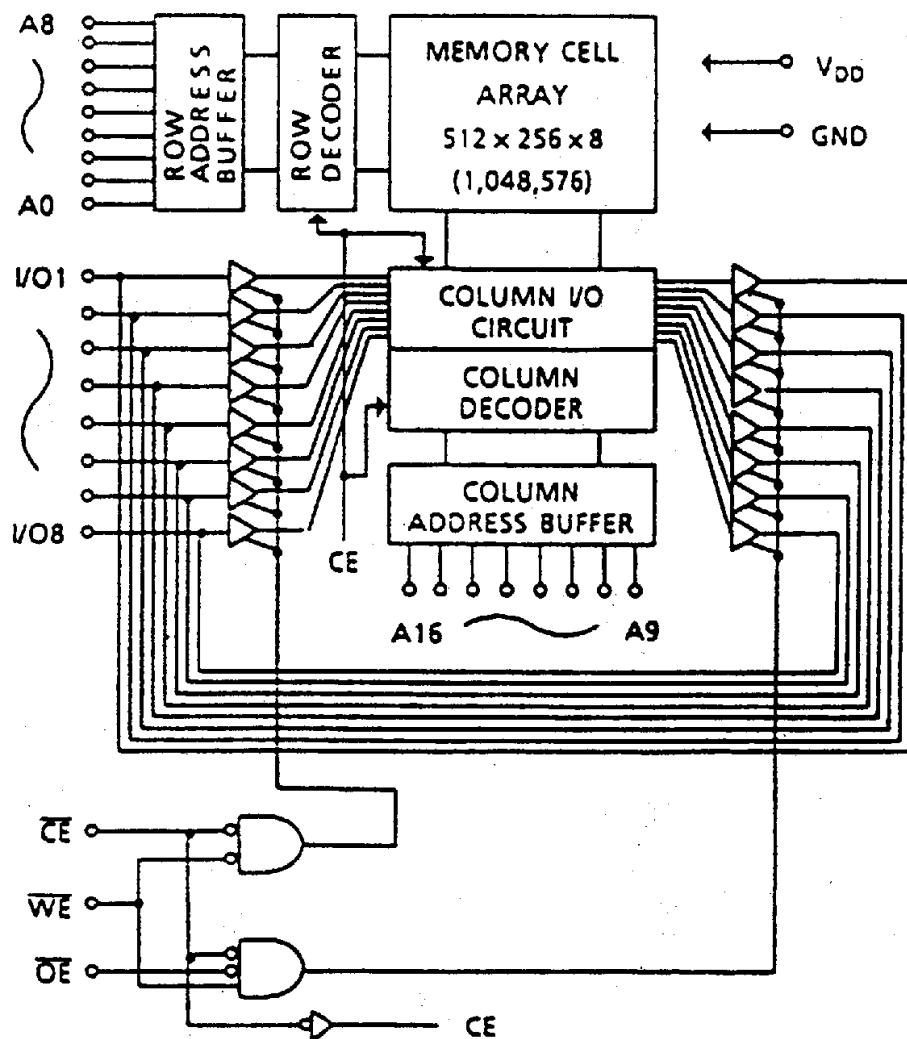
- Fast access time
    - TC55B8128P/J-12 12ns (max.)
    - TC55B8128P/J-15 15ns (max.)
    - TC55B8128P/J-20 20ns (max.)
  - Low power dissipation
    - Operation: 150mA (max.)
    - TC55B8128P/J-12 150mA (max.)
    - TC55B8128P/J-15 150mA (max.)
    - TC55B8128P/J-20 150mA (max.)
    - Standby: 15mA (max.)
  - Single 5V power supply:  $5V \pm 10\%$
  - Fully static operation
  - Inputs and outputs TTL compatible
  - Output buffer control:  $\overline{OE}$
  - Package:
    - TC55B8128P: DIP32-P-400
    - TC55B8128J: SOJ32-P-400A

### Pin Connection (Top View)



A0 ~ A16	Address Inputs
I/O1 ~ I/O8	Data Inputs/Outputs
CE	Chip Enable Input
WE	Write Enable Input
OE	Output Enable Input
V <sub>DD</sub>	Power (+5V)
GND	Ground

## Block Diagram



## Operating Mode

MODE	PIN	CE	OE	WE	I/O	POWER
Read		L	L	H	Output	$I_{DDO}$
Write		L	*	L	Input	$I_{DDO}$
Output Disabled		L	H	H	High-Z	$I_{DDO}$
Standby		H	*	*	High-Z	$I_{DDS}$

\*H or L

## Maximum Ratings

SYMBOL	ITEM	RATING	UNIT
$V_{DD}$	Power Supply Voltage	-0.5 ~ 7.0	V
$V_{IN}$	Input Voltage	-2.0* ~ 7.0	V
$V_{I/O}$	Input/Output Voltage	-0.5* ~ $V_{DD} + 0.5$	V
$P_D$	Power Dissipation	900	mW
$T_{SOLDER}$	Soldering Temperature • Time	260 • 10	°C • sec
$T_{STRG}$	Storage Temperature	-65 ~ 150	°C
$T_{OPR}$	Operating Temperature	-10 ~ 85	°C

\* 3V with a pulse width of 10ns

**DC Recommended Operating Conditions**

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
$V_{DD}$	Power Supply Voltage	4.5	5.0	5.5	V
$V_{IH}$	Input High Voltage	2.2	-	$V_{DD} + 0.5$	V
$V_{IL}$	Input Low Voltage	-0.5*	-	0.8	V

\* -3V with a pulse width of 10ns

**DC Characteristics ( $T_a = 0 \sim 70^\circ C$ ,  $V_{DD} = 5V \pm 10\%$ )**

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
$I_{LI}$	Input Leakage Current	$V_{IN} = 0 \sim V_{DD}$	-	-	$\pm 10$	$\mu A$
$I_{LO}$	Output Leakage Current	$CE = V_{IH}$ or $WE = V_{IL}$ or $OE = V_{IH}$ , $V_{OUT} = 0 \sim V_{DD}$	-	-	$\pm 10$	$\mu A$
$I_{OH}$	Output High Current	$V_{OH} = 2.4V$	-4	-	-	$mA$
$I_{OL}$	Output Low Current	$V_{OL} = 0.4V$	8	-	-	$mA$
$I_{DDO}$	Operating Current	$t_{cycle} = \text{Min cycle},$ $CE = V_{IL}$ , $I_{OUT} = 0mA$ , Other Inputs = $V_{IH}/V_{IL}$	-	-	150	$mA$
$I_{DDS1}$	Standby Current	$CE = V_{IH},$ Other Inputs = $V_{IH}/V_{IL}$	-	-	30	$mA$
$I_{DDS2}$		$CE = V_{DD} - 0.2V,$ Other Inputs = $V_{DD} - 0.2V$ or $0.2V$	-	-	15	

**Capacitance\* ( $T_a = 25^\circ C$ ,  $f = 1.0MHz$ )**

SYMBOL	PARAMETER	TEST CONDITION	MAX.	UNIT
$C_{IN}$	Input Capacitance	$V_{IN} = GND$	6	pF
$C_{I/O}$	Input/Output Capacitance	$V_{I/O} = GND$	8	pF

\*This parameter is periodically sampled and is not 100% tested.

AC Characteristics ( $T_a = 0 \sim 70^\circ C$ <sup>(1)</sup>,  $V_{DD} = 5V \pm 10\%$ )

## Read Cycle

SYMBOL	PARAMETER	TC55B8128P/J-12		TC55B8128P/J-15		TC55B8128P/J-20		UNIT ns
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
$t_{RC}$	Read Cycle Time	12	-	15	-	20	-	
$t_{ACC}$	Address Access Time	-	12	-	15	-	20	
$t_{CO}$	Chip Enable Access Time	-	12	-	15	-	20	
$t_{OE}$	Output Enable Access Time	-	7	-	8	-	10	
$t_{COE}$	Output Enable Time from $\overline{CE}$	4	-	4	-	4	-	
$t_{COD}$	Output Disable Time from $\overline{CE}$	-	6	-	7	-	8	
$t_{OEE}$	Output Enable Time from $\overline{OE}$	0	-	0	-	0	-	
$t_{ODO}$	Output Disable Time from $\overline{OE}$	-	5	-	6	-	7	
$t_{OH}$	Output Data Hold Time from Address Change	4	-	4	-	4	-	

## Write Cycle

SYMBOL	PARAMETER	TC55B8128P/J-12		TC55B8128P/J-15		TC55B8128P/J-20		UNIT ns
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
$t_{WC}$	Write Cycle Time	12	-	15	-	20	-	
$t_{WP}$	Write Pulse Width	8	-	9	-	10	-	
$t_{AW}$	Address Valid to End of Write	9	-	10	-	11	-	
$t_{CW}$	Chip Enable to End of Write	8	-	9	-	10	-	
$t_{AS}$	Address Setup Time	0	-	0	-	0	-	
$t_{WR}$	Write Recovery Time	1	-	1	-	1	-	
$t_{OEW}$	Output Enable Time from $\overline{WE}$	1	-	1	-	1	-	
$t_{ODW}$	Output Disable Time from $\overline{WE}$	-	6	-	7	-	8	
$t_{DS}$	Data Setup Time	7	-	8	-	9	-	
$t_{DH}$	Data Hold Time	0	-	0	-	0	-	

## AC Test Conditions

Input Pulse Levels	3.0V/0.0V
Input Pulse Rise and Fall Time	3ns
Input Timing Measurement Reference Levels	1.5V
Output Timing Measurement Reference Levels	1.5V
Output Load	Fig. 1

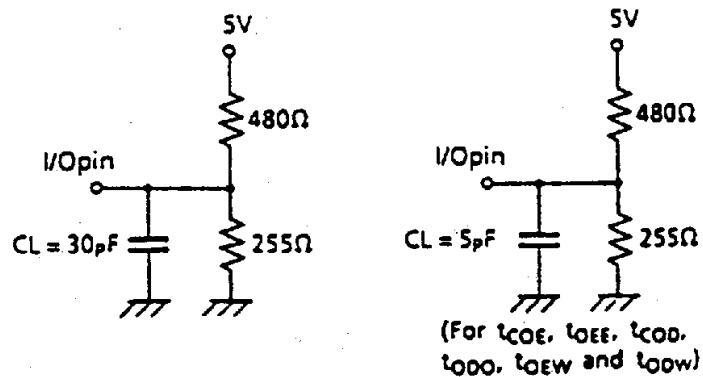
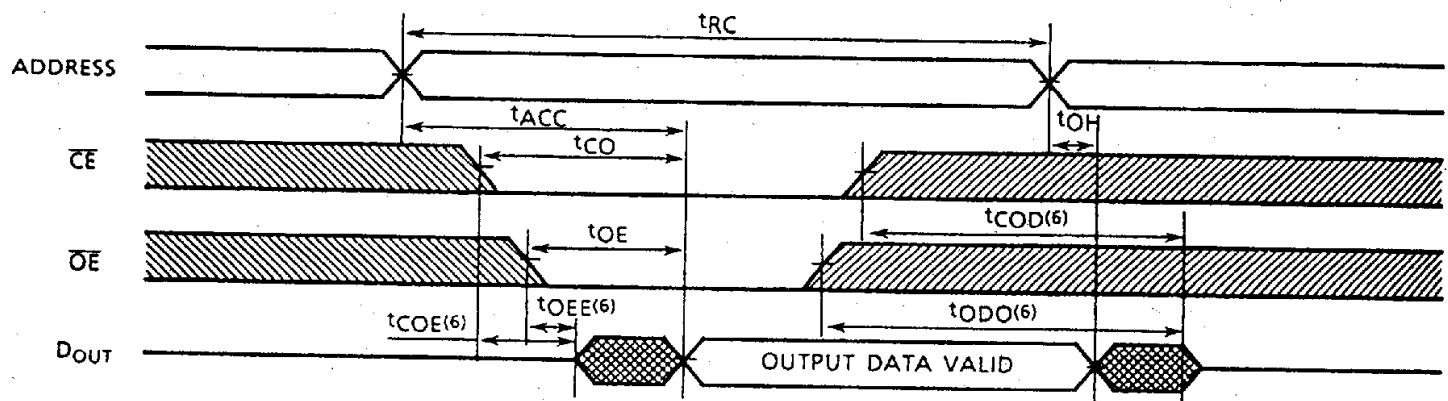
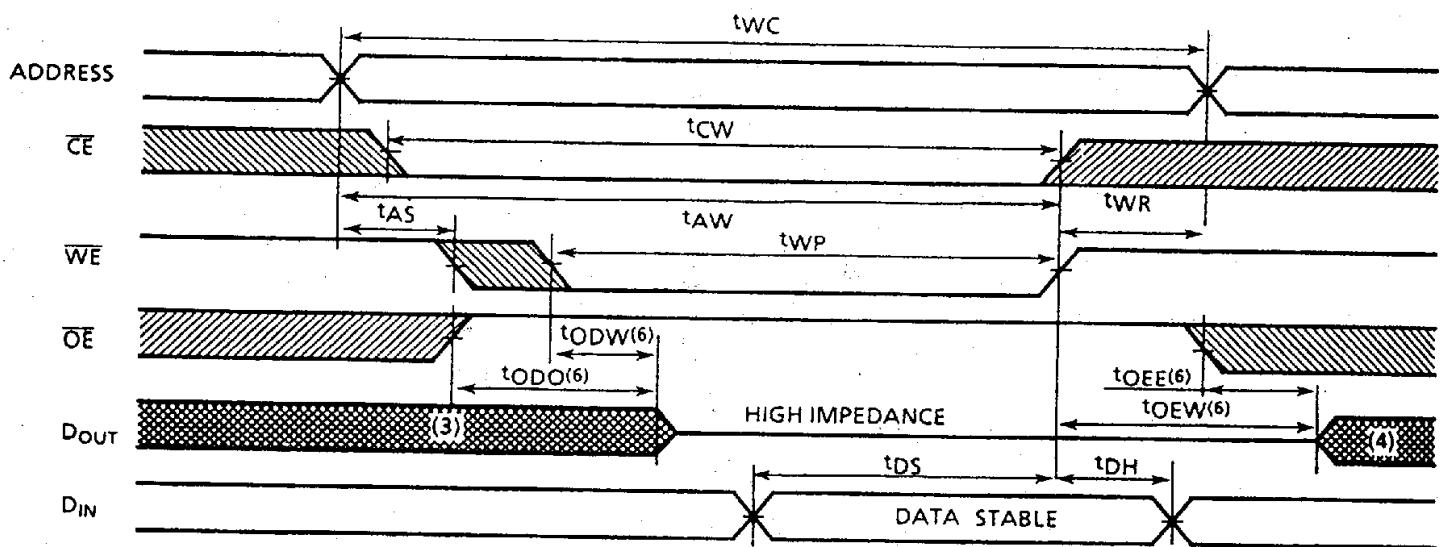
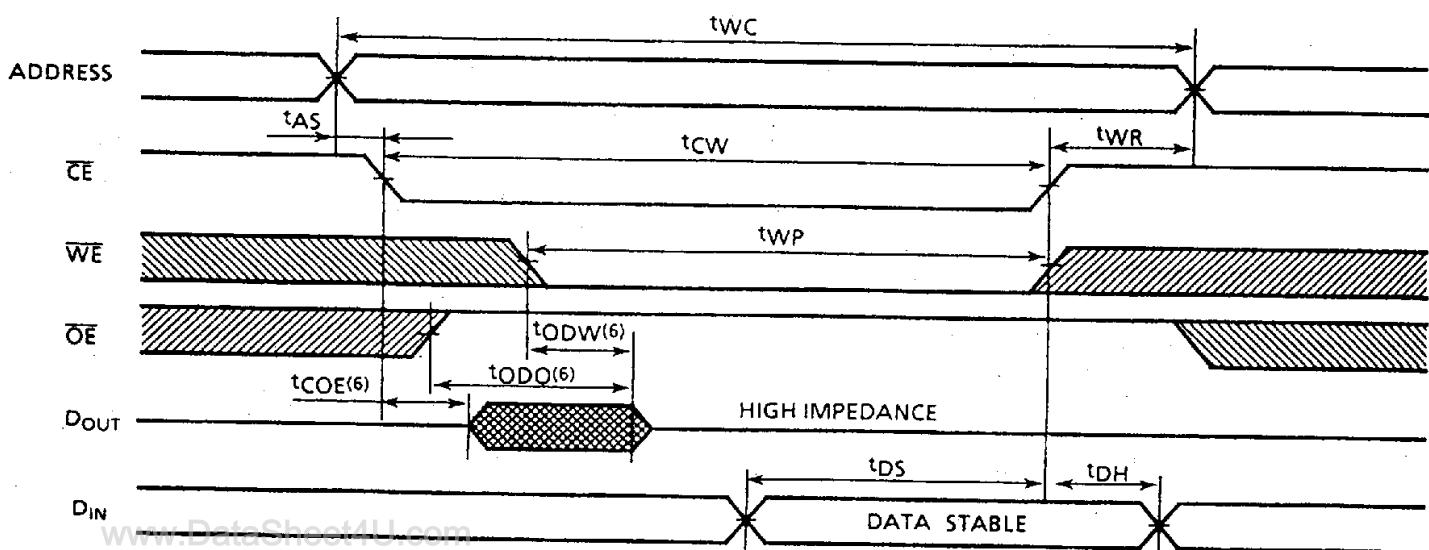


Figure 1.

**Timing Waveforms****Read Cycle (2)****Write Cycle 1 (5) (WE Controlled Write)****Write Cycle 2 (5) (CE Controlled Write)**

## Notes:

1. The operating temperature ( $T_a$ ) is guaranteed with transverse air flow exceeding 400 linear feet per minute.
2.  $\overline{WE}$  is high for read cycles.
3. If the  $\overline{CE}$  low transition occurs coincident with or after the  $\overline{WE}$  low transition, outputs remain in a high impedance state.
4. If the  $\overline{CE}$  high transition occurs coincident with or prior to the  $\overline{WE}$  high transition, outputs remain in a high impedance state.
5. If  $\overline{OE}$  is high during a write cycle, the outputs are in a high impedance state during this period.
6. The following parameters are measured using the load shown in Fig. 1.
  - (A)  $t_{OE}$ ,  $t_{OEE}$ ,  $t_{OEW}$  . . . . . Output Enable Time
  - (B)  $t_{OD}$ ,  $t_{ODO}$ ,  $t_{ODW}$  . . . . . Output Disable Time

